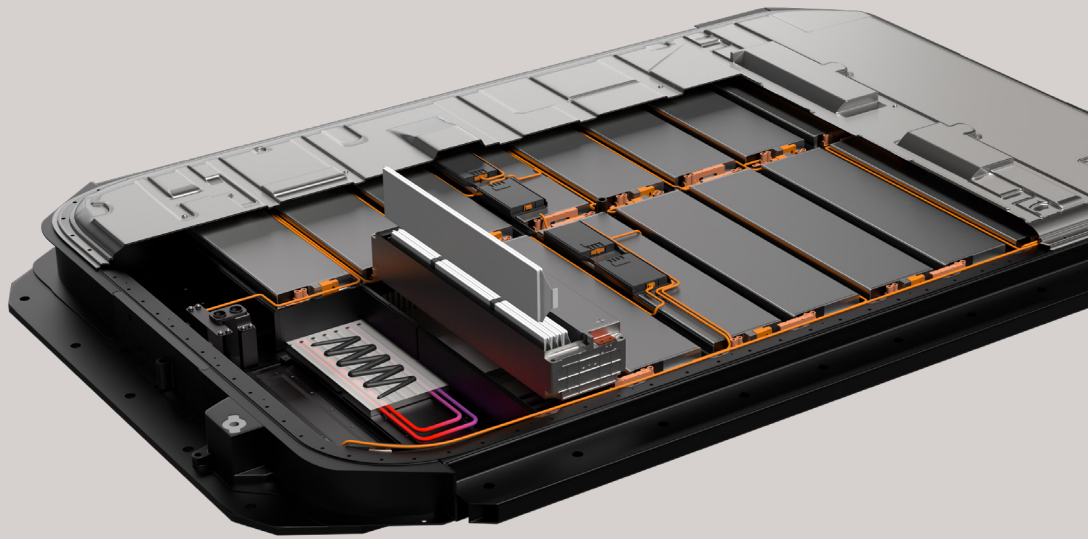
LOCTITE® BERGQUIST®

BERGQUIST® TGF 2030APS

Non-silicone, two-component, room temperature curable, stick-on thermal gap filler for high throughput EV battery assembly applications.

Features & Benefits

- Thermal conductivity: 1.7 W/mK
- Very high dispense rate: >40cc/sec
- Room temperature curing
- High elongation at break: 70%
- Lap shear strength: 0.7MPa
- Low compression stress during assembly



Henkel

eMOBILITY
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BERGQUIST® TGF 2030APS

Typical Applications

- Module or cell stack to cooling plate

Sustainability

- Designed for E-Mobility applications
- Silicone-free
- Low-emission production

Available Configurations*

- Cartridges: 400 mL
- Drum Kits: 140 L, 170 L, 180 L (returnable)

Technical Data

Properties	Typical Value	Test Methods
Chemistry	Silane Modified Polymer	-
Thermal Conductivity	1.7 W/mK	ASTM D5470
Density	1.89	ISO 1183-1
Lap Shear Strength	0.7 MPa	DIN EN 1465
Dielectric Strength	17.6 kV/mm	ASTM D149
Elongation at Break	70%	ISO 527-2

Product Availability*

- Europe

*Availability may change due to high demand. Please contact us for the latest information.

CLICK HERE TO LEARN MORE

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